GT25-S Soft Graphene Based Thermal Interface Material and Heatspreader

Features:

- Low contact resistance
- High compressibility
- Easy-to-use
- Good flexibility

Applications:

IGBT, GPU, CPU, LED, RF, Opto and power module cooling

Order status: Large amount available now

Description:

GT25-S is a highly soft graphene based thermal interface material. It has very low contact thermal resistance (10-20 Kmm^2/W at 100 –400 KPa). Moreover, the GT25-S has advantages of low weight, low complexity during assembly and good maintainability. GT25-S thus opens new opportunities for addressing large heat dissipation issues in electronics and other high power driven systems.

Physical Properties	Value	Units	Test Method
Size	□ 4*4	cm^2	
Thickness	0.25-0.5(± 15%)	mm	
Roughness	<5	%	
Color	Grey		
Filler Material	Graphene		
Density	0.6	g/cm^3	
Compressibility	30-40	%	ASTM
Recovery	15-20	%	ASTM
Compressive Strength	100	KPa	ASTM
Temperature Range	-40 to 200	°C	
Bulk Through-plane Thermal Conductivity	350-450	W/mK	LFA447
Effective Thermal Conductivity	24-25 (100 KPa)	W/mK	ASTM
Thermal Resistance	20 (100 KPa) 10 (400 KPa)	Kmm^2/W	ASTM
Bulk In-plane (parallel to alignment) Thermal Conductivity	350-450	W/mK	LFA447
Bulk In-plane (perpendicular to alignment) Thermal Conductivity	1-2	W/mK	LFA447
Specific Heat	0.2-0.3	J/g.K	Hotdisk
Minimum in-plane tensile strength	40	KPa	ASTM

SHT Smart High Tech AB
Post address: Kemivägen 6, SE 412
58 Göteborg, Sweden

SHT
-Make it cool-

Phone: +46(0)76 948 99 96
Email: info@sht-tek.com

www.sht-tek.com

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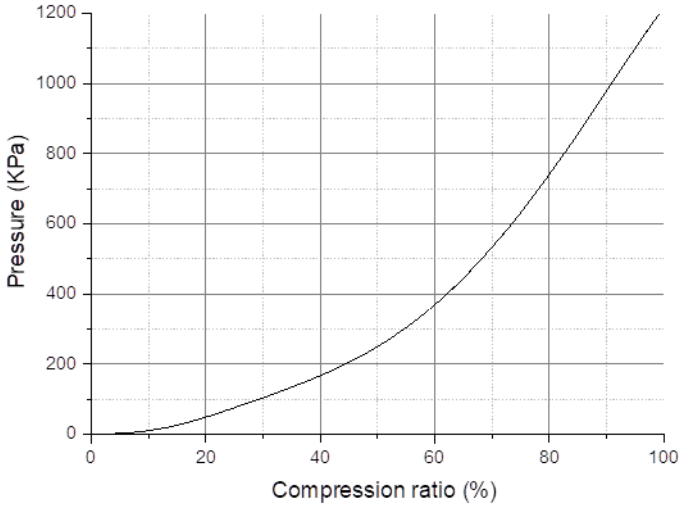
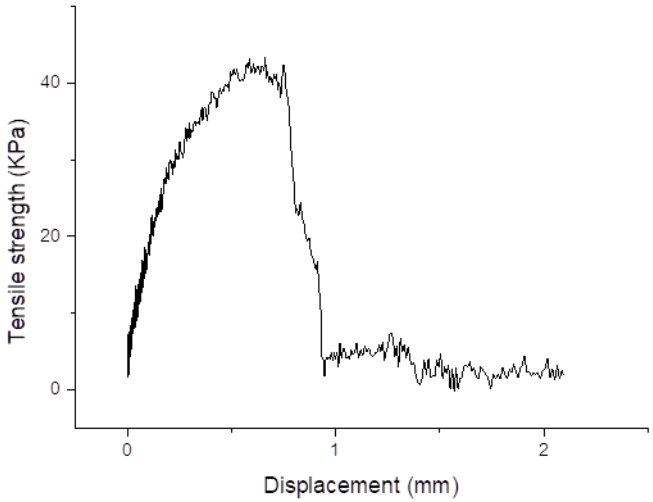
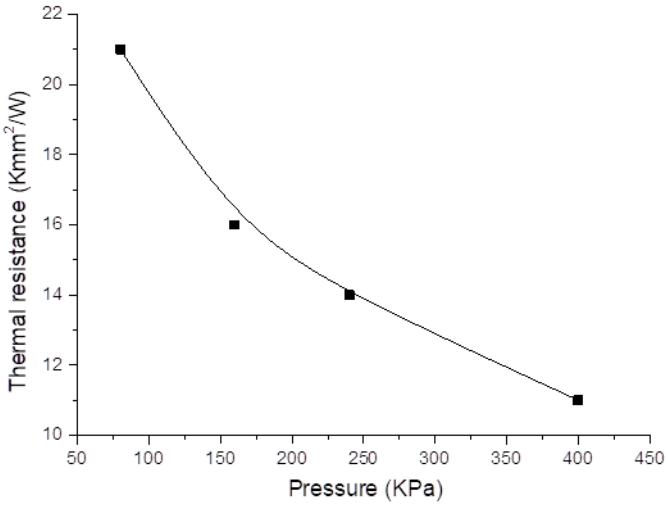
Compression ratios of GT25-S at different pressures:



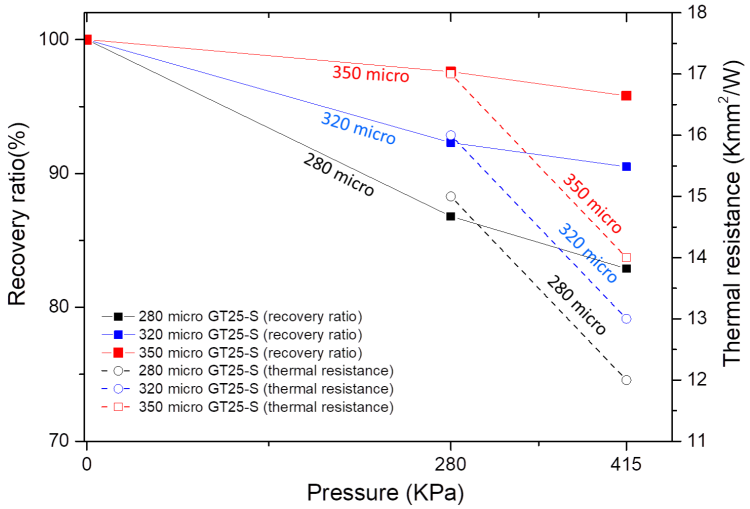
Tensile strength of GT25-S



Thermal resistance of GT25-S at different pressures:



Recovery ratio of GT25-S at different thickness:



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